



# P-channel 30 V, 0.024 Ω typ., 6 A, STripFET<sup>TM</sup> VI DeepGATE<sup>TM</sup> Power MOSFET in a SO-8 package

Datasheet - preliminary data

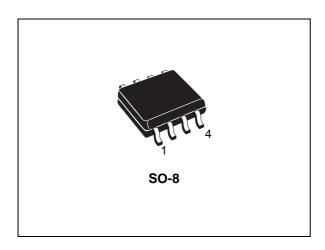
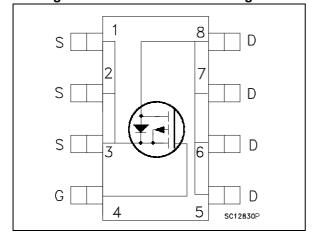


Figure 1. Internal schematic diagram



#### **Features**

Order code	$V_{DS}$	R <sub>DS(on)</sub> max	I <sub>D</sub>
STS6P3LLH6	30 V	0.03 Ω	6 A

- R<sub>DS(on)</sub>\* Q<sub>g</sub> industry benchmark
- Extremely low on-resistance R<sub>DS(on)</sub>
- · High avalanche ruggedness

#### **Applications**

· Switching applications

#### **Description**

This device is an N-channel Power MOSFET developed using the  $6^{th}$  generation of STripFET<sup>TM</sup> DeepGATE<sup>TM</sup> technology, with a new gate structure. The resulting Power MOSFET exhibits the lowest R<sub>DS(on)</sub> in all packages.

**Table 1. Device summary** 

Order code	Marking	Packages	Packaging
STS6P3LLH6	6K3L	SO-8	Tape and reel

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed.

Contents STS6P3LLH6

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STS6P3LLH6 Electrical ratings

## 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	30	V
V <sub>GS</sub>	Gate- source voltage	±20	V
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>amb</sub> = 25°C	6	Α
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at T <sub>amb</sub> = 100°C	4	Α
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	24	Α
P <sub>TOT</sub> <sup>(1)</sup>	Total dissipation at T <sub>amb</sub> = 25°C	2.7	W
T <sub>stg</sub>	Storage temperature	-55 to 150	°C
Tj	Operating junction temperature	150	°C

<sup>1.</sup> This value is rated according to  $R_{thj-amb}$ 

Table 3. Thermal data

Symbol	Parameter	Value	Unit	
R <sub>thj-amb</sub> (1)	Thermal resistance junction-amb	47	°C/W	

<sup>1.</sup> When mounted on 1 inch<sup>2</sup> FR-4 board, 2 oz. Cu.,  $t \le 10$  sec

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed.

<sup>2.</sup> Pulse width limited by safe operating area

Electrical characteristics STS6P3LLH6

## 2 Electrical characteristics

(T<sub>CASE</sub> = 25 °C unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	I <sub>D</sub> = 250 μA	30			V V
1	Zero gate voltage	V <sub>DS</sub> = 30 V			1	μA
I <sub>DSS</sub>	drain current ( $V_{GS} = 0$ )	V <sub>DS</sub> =30 V, T <sub>C</sub> =125 °C				
I <sub>GSS</sub>	Gate-body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ±20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1			V
D	Static drain-source on-	$V_{GS} = 10 \text{ V}, I_{D} = 3 \text{ A}$		0.024	0.03	Ω
R <sub>DS(on)</sub>	resistance	$V_{GS} = 4.5 \text{ V}, I_D = 3 \text{ A}$	·	0.038	0.05	Ω

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
C <sub>iss</sub>	Input capacitance		-	1450	-	pF
C <sub>oss</sub>	Output capacitance	$V_{DS} = 24 \text{ V, f} = 1 \text{ MHz,}$	-	178	-	pF
C <sub>rss</sub>	Reverse transfer capacitance	$V_{GS} = 0$	-	120	-	pF
Qg	Total gate charge	V <sub>DD</sub> =24 V I <sub>D</sub> =6 A V <sub>GS</sub> = 4.5 V	-	12	-	nC
Q <sub>gs</sub>	Gate-source charge		-	4.4	-	nC
Q <sub>gd</sub>	Gate-drain charge	·65 ·	-	5	-	nC

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time		-	15	-	ns
t <sub>r</sub>	Rise time	$V_{DD} = 24 \text{ V}, I_D = 3 \text{ A}$ $R_{G} = 4.7 \Omega, V_{GS} = 10 \text{ V}$	-	15	-	ns
t <sub>d(off)</sub>	Turn-off delay time	$R_G=4.7 \Omega$ , $V_{GS}=10 V$ Figure 13	-	24	-	ns
t <sub>f</sub>	Fall time		-	21	-	ns

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed

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Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I <sub>SD</sub>	Source-drain current		-		6	Α
I <sub>SDM</sub> <sup>(1)</sup>	Source-drain current (pulsed)		-		24	Α
V <sub>SD</sub> (2)	Forward on voltage	$I_{SD} = 3A, V_{GS} = 0$	-		1.1	V
t <sub>rr</sub>	Reverse recovery time		-	15		ns
Q <sub>rr</sub>	Reverse recovery charge	I <sub>SD</sub> = 3 A, di/dt = 100 A/μs V <sub>DD</sub> =16 V, T <sub>i</sub> =150 °C	-	6.5		nC
I <sub>RRM</sub>	Reverse recovery current	, , , , , , , , , , , , , , , , , , ,	-	0.9		Α

<sup>1.</sup> Pulse width limited by safe operating area.

Note: For the P-channel MOSFET actual polarity of voltages and current has to be reversed



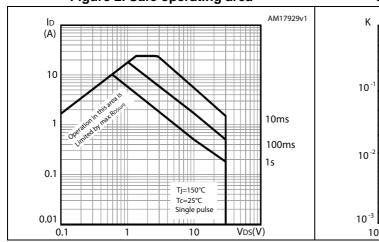
<sup>2.</sup> Pulsed: Pulse duration =  $300 \mu s$ , duty cycle 1.5%

Electrical characteristics STS6P3LLH6

### 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

Figure 3. Thermal impedance



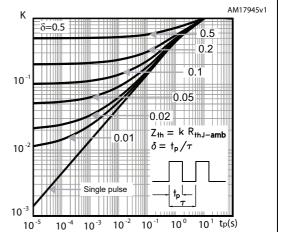
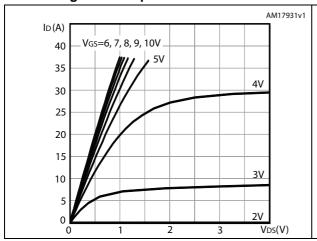


Figure 4. Output characteristics

Figure 5. Transfer characteristics



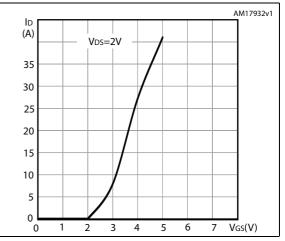
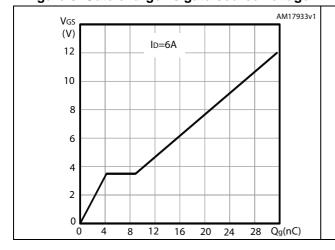
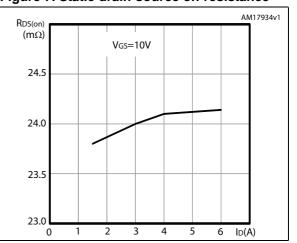


Figure 6. Gate charge vs gate-source voltage

Figure 7. Static drain-source on-resistance



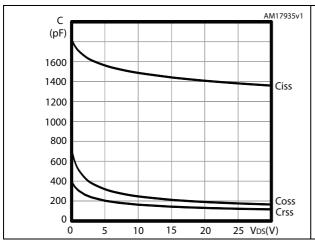


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Figure 8. Capacitance variations

Figure 9. Normalized gate threshold voltage vs temperature



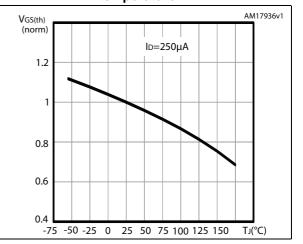
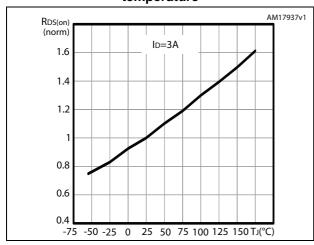


Figure 10. Normalized on-resistance vs temperature

Figure 11. Normalized  $V_{\text{DS}}$  vs temperature



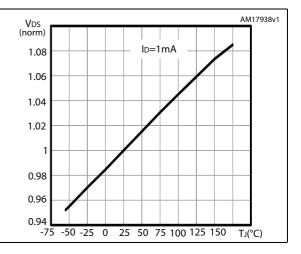
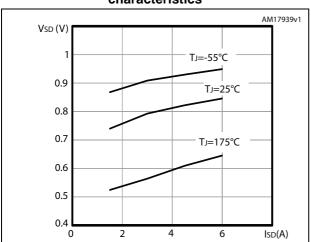


Figure 12. Source-drain diode forward characteristics



Test circuits STS6P3LLH6

## 3 Test circuits

Figure 13. Switching times test circuit for resistive load

Figure 14. Gate charge test circuit

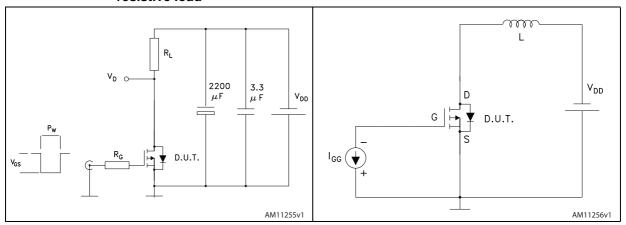
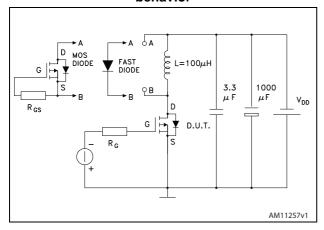


Figure 15. Test circuit for diode recovery behavior



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## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.



Table 8. SO-8 mechanical data

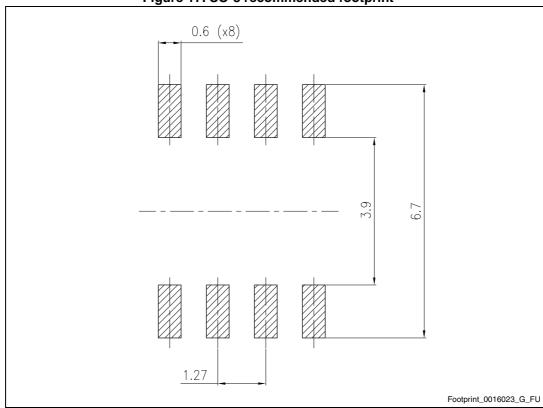
Dim		mm	
Dim. —	Min.	Тур.	Max.
А			1.75
A1	0.10		0.25
A2	1.25		
b	0.31		0.51
b1	0.28		0.48
С	0.10		0.25
c1	0.10		0.23
D	4.80	4.90	5.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
е		1.27	
h	0.25		0.50
L	0.40		1.27
L1		1.04	
L2		0.25	
k	0°		8°
ccc			0.10

SECTION B-B

Figure 16. SO-8 drawing



BASE METAL



a. All dimensions are in millimeters.



0016023\_G\_FU

# 5 Packaging mechanical data

Table 9. SO-8 tape and reel mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
Α			330
С	12.8		13.2
D	20.2		
N	60		
Т			22.4
Ao	8.1		8.5
Во	5.5		5.9
Ko	2.1		2.3
Po	3.9		4.1
Р	7.9		8.1

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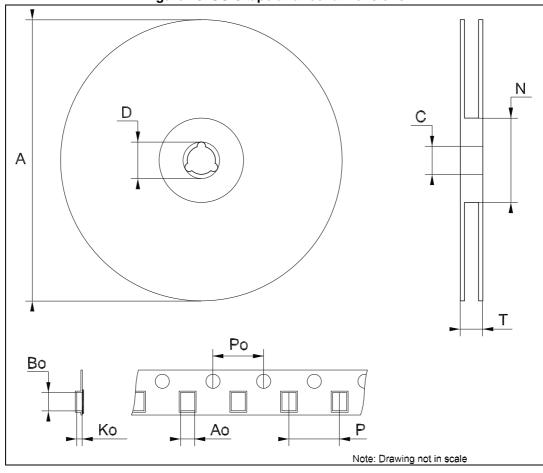


Figure 18. SO-8 tape and reel dimensions

Revision history STS6P3LLH6

# 6 Revision history

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Table 10. Revision history

Date	Revision	Changes
01-Feb-2013	1	First revision.
28-Nov-2013	2	<ul> <li>Modified: R<sub>DS(on)</sub> value in cover page</li> <li>Modified: V<sub>GS</sub> value in <i>Table 2</i></li> <li>Modified: IGSS test conditions value in <i>Table 4</i></li> <li>Modified: Q<sub>g</sub> typical value in <i>Table 5</i></li> <li>Added: Section 2.1: Electrical characteristics (curves)</li> <li>Minor text changes</li> </ul>

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